



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: G9911-05 DATE: November 18, 1999 Product Affected: All Plastic packages Manufacturing Location Affected: ALL Date Effective: February 18, 2000	MEANS OF DISTINGUISHING CHANGED DEVICES: <input type="checkbox"/> Product Mark <input type="checkbox"/> Back Mark <input type="checkbox"/> Date Code <input checked="" type="checkbox"/> Other: "assembly cut-off lot number"
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Contact: PS Tow Title: Corporate Quality / Reliability Manager Phone #: (408) 492-8206 Fax #: (408) 727-2328 E-mail: pstow@idt.com	Additional Data: Samples:
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DESCRIPTION AND PURPOSE OF CHANGE:

<input type="checkbox"/> Die Technology	
<input type="checkbox"/> Wafer Fabrication Process	Add Shinetsu KMC184 and KMC184VA (low alpha version) family and Sumitomo
<input type="checkbox"/> Assembly Process	EME-6730 and EME-9730 (low alpha version) family as qualified mold compound for
<input type="checkbox"/> Equipment	all plastic packages.
<input checked="" type="checkbox"/> Material	
<input type="checkbox"/> Testing	
<input type="checkbox"/> Manufacturing Site	
<input type="checkbox"/> Data Sheet	

RELIABILITY/QUALIFICATION SUMMARY:
Please see attached qualification reports (Attachments 1, 2, 3 & 4)

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:
IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

Customer: _____	<input type="checkbox"/> <i>Approval for shipments prior to effective date.</i>
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

RECD. BY: _____ DATE: _____



Integrated Device Technology, Inc.

Attachment # 1 PCN # G9911-05

Reliability Qualification Report

I. QUAL DESCRIPTION

Qual Type : NEW ASSEMBLY TECHNIQUE
Qual Objective : QUALIFICATION OF LOW STRESS MOLD COMPOUNDS KMC-184-9 / ARAT 2184-9

II. QUAL VEHICLE

	Lot#1	Lot#2	Lot#3	Lot#4
Product Group	LOGIC	SRAM	SMP	MPR
Device Type	316233ZQ	71V124N	70V3579Z	79RV465X
Die Size	40 x 172 mils	175 x 196 mils	302 x 404 mils	239 x 154 mils
Wafer Lot #	P4772-9700	S449130552	449150680A	S448470233E
Assembly Lot #	QEK28442	EB10978	EI47028	EI44239
Package Type	PA56 (56 Leads TSSOP)	PH32 (32 Leads TSOP)	DR208 (PQFP 208)	DP208 (PQFP 208)
Body Size	6.1 x 14.0 mm	10.16 x 20.95 mm	28.0 x 28.0 mm	28 x 28 mm
Package Thickness	1.0 mm	1.0 mm	3.4 mm	3.4 mm
Lead Pitch	0.50 mm	1.27 mm	0.50 mm	0.50 mm
Lead frame type	OLIN C7025	OLIN C7025	Olin C7025	C7025 (Copper)
Lead frame thickness	6 mils	5 mils	6 mils	6 mils
Die Pad Size	98 x 220 mils	220 x 257 mils	433 x 433 mils	276 x 276 mils
Heat Slug	n/a	n/a	n/a	Cu-Ni/Black Oxide (Exposed)
Die Attach Material	8390 (ABLESTIK)	8390 (ABLESTIK)	84-ILMIS R4 (ABLESTIK)	8361J (ABLESTIK)
Wire Bond	GL-2 1.0 mil Au (TANAKA)	GL-2 1.0 mil Au (TANAKA)	M3 1.3 mil Au (TANAKA)	1.0mil Long Loop Au (MIKYEONG)
Mold Compound	Arat 2184-9 (CIBA GEIGY)	KMC 184-9 (SHINETSU)	KMC 184-9 (SHINETSU)	KMC 184-9 (SHINETSU)
Lead Finish	SnPb Plating	SnPb Plating	SnPb Plating	SnPb Plating
Assembly Location	IDT-Phils	CHIP PAC KOREA	ANAM	ANAM



Integrated Device Technology, Inc.

Attachment # 2 PCN # G9911-05

Reliability Qualification Report

III. QUALIFICATION MATRIX DATA and RESULTS

Test	Description	QL* ACC/SS	TEST POINT	Assy #	#REF!	#REF!	#REF!	#REF!	#REF!
					#REF! QUAL RESULTS	#REF! QUAL RESULTS	#REF! QUAL RESULTS	#REF! QUAL RESULTS	#REF! QUAL RESULTS
B5	STEAM PRESSURE POT TEST (SPP) : Unbiased, Saturated Steam, 2 Atm., 121 °C + END POINT ELECTRICAL TEST	0/45	Preconditioning 168 hrs		0/45	0/45	0/45	-	-
B6A	BAKE & BALL SHEAR TEST : IDT Spec MAC-3057 (Ball shear strength > 40 g @ 48 hrs)	0/5	-		0/5	-	0/5	0/5	0/5
B6B	WIRE PULL TEST : IDT Spec MAC-3010 (Bond pull strength > 5.0 grams)	0/5	-		0/5	-	0/5	0/5	-
B7	X-RAY : IDT Spec. MAC-3012 (Package voids, Die attach voids and Wire sweep)	0/45	-		0/45	0/45	0/45	0/45	-
B8	SAT CSAM ANALYSIS : IDT Spec MAC-3070	0/10	-		0/10	0/10	0/10	0/10	0/10
B10	EXTERNAL VISUAL INSPECTION : Mil-Std-883, Method 2009	0/25	-		0/25	0/25	0/25	0/25	0/25
B11	INTERNAL VISUAL INSPECTION : Mil-Std-883, Method 2010	0/5	-		0/5	0/5	0/5	0/5	0/5
B13	MOISTURE CLASSIFICATION : IDT Spec QCA-1416	0/30	-		0/30	0/30	0/30	0/30	0/30
Group C : Package / Die Integrity									
Test	Description								
C2B	HIGHLY ACCELERATED STRESS TEST (HAST), Vcc max static bias, TA = 130°C/85% RH + END POINT ELECTRICAL TEST	0/45	Preconditioning 100 hrs		0/45	-	0/45	0/45	0/45
C4	HIGH TEMPERATURE STABILIZATION BAKE (HTSB) : TA = 150 °C + END POINT ELECTRICAL TEST	0/45	500 hrs 1000 hrs		-	-	0/77	0/77	0/77
Group D : Package Design									
Test	Description								
D3	TEMPERATURE CYCLE (T/C) : Mil-Std-883, Method 1010, Cond. C (-65°C to 150°C) + END POINT ELECTRICAL TEST	0/45	Preconditioning 500 cyc		0/45	0/45	0/45	0/45	0/45

QL* - Quality Level, number of units
S.A.T. - Scanning Acoustic Tomography

Corporate QA/Rel Engineering



Integrated Device Technology, Inc.

Attachment # 3 PCN # G9911-05

Reliability Qualification Report

I. QUAL DESCRIPTION

Qual Type : NEW ASSEMBLY TECHNIQUE
Qual Objective : QUALIFICATION OF LOW STRESS MOLD COMPOUNDS EME-6730UC

II. QUAL VEHICLE

	Lot#1	Lot#2	Lot#3
Product Group	SRAM	SRAM	MPR
Device Type	71V016N	71016N	79RV465X
Die Size	175 x 196 mils	175 x 196 mils	239 x 154 mils
Wafer Lot #	S448090340	448460141	S448470233E
Assembly Lot #	QEK24915	QEK24870N	EI44240
Package Type	PB44 (44 Leads SOJ)	PB44 (44 Leads SOJ)	DP208 (PQFP 208)
Body Size	400 x 1125 mils	400 x 1125 mils	28 x 28 mm
Package Thickness	113 mils	113 mils	3.4 mm
Lead Pitch	50 mils	50 mils	0.50 mm
Lead frame type	Olin 194	Olin 194	C7025 (Copper)
Lead frame thickness	10 mils	10 mils	6 mils
Die Pad Size	275 x 235 mils	275 x 235 mils	276 x 276 mils
Heat Slug	n/a	n/a	Cu-Ni/Black Oxide (Exposed)
Die Attach Material	8390 (ABLESTIK)	8390 (ABLESTIK)	8361J (ABLESTIK)
Wire Bond	M3 1.3 mil Au (TANAKA)	M3 1.3 mil Au (TANAKA)	1.0mil Long Loop Au (MIKYEONG)
Mold Compound	EME-6730UC (SUMITOMO)	EME-6730UC (SUMITOMO)	EME-6730UC (SUMITOMO)
Lead Finish	SnPb Plating	SnPb Plating	SnPb Plating
Assembly Location	IDT-Phils	IDT-Phils	ANAM



Integrated Device Technology, Inc.

Attachment # 4 PCN # G9911-05

Reliability Qualification Report

III. QUALIFICATION MATRIX DATA and RESULTS

Test	Description	QL* ACC/SS	TEST POINT	Assy #		
				#REF!	#REF!	#REF!
Group B : Package / Process						
B6A	BAKE & BALL SHEAR TEST : IDT Spec MAC-3057 (Ball shear strength > 40 g @ 48 hrs)	0/5	-	0/5	0/5	0/5
B6B	WIRE PULL TEST : IDT Spec MAC-3010 (Bond pull strength > 5.0 grams)	0/5	-	0/5	0/5	-
B7	X-RAY : IDT Spec. MAC-3012 (Package voids, Die attach voids and Wire sweep)	0/45	-	0/45	0/45	-
B8	SAT CSAM ANALYSIS : IDT Spec MAC-3070	0/10	-	0/10	0/10	0/10
B10	EXTERNAL VISUAL INSPECTION : Mil-Std-883, Method 2009	0/25	-	0/25	0/25	0/25
B11	INTERNAL VISUAL INSPECTION : Mil-Std-883, Method 2010	0/5	-	0/5	0/5	0/5
B13	MOISTURE CLASSIFICATION : IDT Spec QCA-1416	0/30	-	0/30	0/30	0/30
Group C : Package / Die Integrity						
Test	Description					
C1	LIFE TEST : Mil-Std-883, Method 1005 (Dynamic B/I, Vcc = Vccmax, TA = 135 °C) + END POINT ELECTRICAL TEST	0/77	500 hrs 1000 hrs	0/77 0/77	0/77 0/77	- -
C2B	HIGHLY ACCELERATED STRESS TEST (HAST), Vcc max static bias, TA = 130°C/85% RH + END POINT ELECTRICAL TEST	0/45	Preconditioning 100 hrs	0/45 0/45	0/45 0/45	- -
C4	HIGH TEMPERATURE STABILIZATION BAKE (HTSB) : TA = 150 °C + END POINT ELECTRICAL TEST	0/45	500 hrs 1000 hrs	0/77 0/77	0/77 0/77	- -
Group D : Package Design						
Test	Description					
D2	THERMAL SHOCK (T/S) : Mil-Std-883, Method 1011 Cond. C (-65°C to 150°C) + END POINT ELECTRICAL TEST	0/45	100 cyc	0/45	0/45	-
D3	TEMPERATURE CYCLE (T/C) : Mil-Std-883, Method 1010, Cond. C (-65°C to 150°C) + END POINT ELECTRICAL TEST	0/45	Preconditioning 500 cyc	0/45 0/45	0/45 0/45	0/45 0/45

Notes:

QL* - Quality Level, number of units

S.A.T. - Scanning Acoustic Tomography

Corporate QA/Rel Engineering